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# Understanding <u>Embedded - FPGAs (Field Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

## **Applications of Embedded - FPGAs**

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	225400
Number of Logic Elements/Cells	597000
Total RAM Bits	53248000
Number of I/O	432
Number of Gates	-
Voltage - Supply	0.87V ~ 0.93V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1517-FBGA (40x40)
Supplier Device Package	1517-FBGA (40x40)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5sgxeb6r2f40c2

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

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Table 7. Recommended Transceiver Power Supply Operating Conditions for Stratix V GX, GS, and GT Devices (Part 2 of 2)

Symbol	Description	Devices	Minimum <sup>(4)</sup>	Typical	Maximum <sup>(4)</sup>	Unit
			0.82	0.85	0.88	
V <sub>CCR_GXBR</sub>	Receiver analog power supply (right side)	GX, GS, GT	0.87	0.90	0.93	V
(2)	neceiver analog power supply (right side)	ux, us, u1	0.97	1.0	1.03	v
			1.03	1.05	1.07	
V <sub>CCR_GTBR</sub>	Receiver analog power supply for GT channels (right side)	GT	1.02	1.05	1.08	V
			0.82	0.85	0.88	
V <sub>CCT_GXBL</sub>	Transmitter analog newer cupply (left side)	GX, GS, GT	0.87	0.90	0.93	V
	Transmitter analog power supply (left side)	ux, us, u1	0.97	1.0	1.03	
			1.03	1.05	1.07	
			0.82	0.85	0.88	
V <sub>CCT_GXBR</sub>	Transmitter analog power supply (right side)	GX, GS, GT	0.87	0.90	0.93	V
(2)	Transmitter analog power supply (right side)		0.97	1.0	1.03	
			1.03	0.97         1.0         1.03           1.03         1.05         1.07           1.02         1.05         1.08           0.82         0.85         0.88           0.87         0.90         0.93           0.97         1.0         1.03           1.03         1.05         1.07           0.82         0.85         0.88           0.87         0.90         0.93           0.97         1.0         1.03		
V <sub>CCT_GTBR</sub>	Transmitter analog power supply for GT channels (right side)	GT	1.02	1.05	1.08	V
V <sub>CCL_GTBR</sub>	Transmitter clock network power supply	GT	1.02	1.05	1.08	V
V <sub>CCH_GXBL</sub>	Transmitter output buffer power supply (left side)	GX, GS, GT	1.425	1.5	1.575	V
V <sub>CCH_GXBR</sub>	Transmitter output buffer power supply (right side)	GX, GS, GT	1.425	1.5	1.575	V

#### Notes to Table 7:

<sup>(1)</sup> This supply must be connected to 3.0 V if the CMU PLL, receiver CDR, or both, are configured at a base data rate > 6.5 Gbps. Up to 6.5 Gbps, you can connect this supply to either 3.0 V or 2.5 V.

<sup>(2)</sup> Refer to Table 8 to select the correct power supply level for your design.

<sup>(3)</sup> When using ATX PLLs, the supply must be 3.0 V.

<sup>(4)</sup> This value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

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			Re	esistance			
Symbol	Description	Conditions	C1	C2,I2	C3, I3, I3YY	C4, I4	Unit
50-Ω R <sub>S</sub>	Internal series termination without calibration (50- $\Omega$ setting)	V <sub>CCIO</sub> = 1.8 and 1.5 V	±30	±30	±40	±40	%
50-Ω R <sub>S</sub>	Internal series termination without calibration (50- $\Omega$ setting)	V <sub>CCIO</sub> = 1.2 V	±35	±35	±50	±50	%
100-Ω R <sub>D</sub>	Internal differential termination (100-Ω setting)	V <sub>CCPD</sub> = 2.5 V	±25	±25	±25	±25	%

Calibration accuracy for the calibrated series and parallel OCTs are applicable at the moment of calibration. When voltage and temperature conditions change after calibration, the tolerance may change.

OCT calibration is automatically performed at power-up for OCT-enabled I/Os. Table 13 lists the OCT variation with temperature and voltage after power-up calibration. Use Table 13 to determine the OCT variation after power-up calibration and Equation 1 to determine the OCT variation without recalibration.

Equation 1. OCT Variation Without Recalibration for Stratix V Devices (1), (2), (3), (4), (5), (6)

$$R_{OCT} = R_{SCAL} \Big( 1 + \langle \frac{dR}{dT} \times \Delta T \rangle \pm \langle \frac{dR}{dV} \times \Delta V \rangle \Big)$$

### Notes to Equation 1:

- (1) The  $R_{OCT}$  value shows the range of OCT resistance with the variation of temperature and  $V_{CCIO}$ .
- (2) R<sub>SCAL</sub> is the OCT resistance value at power-up.
- (3)  $\Delta T$  is the variation of temperature with respect to the temperature at power-up.
- (4)  $\Delta V$  is the variation of voltage with respect to the  $V_{CCIO}$  at power-up.
- (5) dR/dT is the percentage change of  $R_{SCAL}$  with temperature.
- (6) dR/dV is the percentage change of  $R_{SCAL}$  with voltage.

Table 13 lists the on-chip termination variation after power-up calibration.

Table 13. OCT Variation after Power-Up Calibration for Stratix V Devices (Part 1 of 2) (1)

Symbol	Description	V <sub>CCIO</sub> (V)	Typical	Unit
		3.0	0.0297	
	007	2.5	0.0344	
dR/dV	OCT variation with voltage without recalibration	1.8	0.0499	%/mV
	Todanstation	1.5	0.0744	
		1.2	0.1241	

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Table 13. OCT Variation after Power-Up Calibration for Stratix V Devices (Part 2 of 2) (1)

Symbol	Description	V <sub>CCIO</sub> (V)	Typical	Unit	
0.07		3.0	0.189		
		2.5	0.208		
dR/dT	OCT variation with temperature without recalibration	1.8	0.266	%/°C	
	Without recalibration	1.5	0.273		
		1.2	0.317		

#### Note to Table 13:

(1) Valid for a  $V_{\text{CCIO}}$  range of  $\pm 5\%$  and a temperature range of  $0^\circ$  to  $85^\circ\text{C}.$ 

## **Pin Capacitance**

Table 14 lists the Stratix V device family pin capacitance.

**Table 14. Pin Capacitance for Stratix V Devices** 

Symbol	Description	Value	Unit
C <sub>IOTB</sub>	Input capacitance on the top and bottom I/O pins	6	pF
C <sub>IOLR</sub>	Input capacitance on the left and right I/O pins	6	pF
C <sub>OUTFB</sub>	Input capacitance on dual-purpose clock output and feedback pins	6	pF

### **Hot Socketing**

Table 15 lists the hot socketing specifications for Stratix V devices.

Table 15. Hot Socketing Specifications for Stratix V Devices

Symbol	Description	Maximum
I <sub>IOPIN (DC)</sub>	DC current per I/O pin	300 μΑ
I <sub>IOPIN (AC)</sub>	AC current per I/O pin	8 mA <sup>(1)</sup>
I <sub>XCVR-TX (DC)</sub>	DC current per transceiver transmitter pin	100 mA
I <sub>XCVR-RX (DC)</sub>	DC current per transceiver receiver pin	50 mA

## Note to Table 15:

(1) The I/O ramp rate is 10 ns or more. For ramp rates faster than 10 ns,  $|I_{IOPIN}| = C dv/dt$ , in which C is the I/O pin capacitance and dv/dt is the slew rate.

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Table 19. Single-Ended SSTL, HSTL, and HSUL I/O Standards Signal Specifications for Stratix V Devices (Part 2 of 2)

I/O Standard	V <sub>IL(D(</sub>	; <sub>)</sub> (V)	V <sub>IH(D</sub>	<sub>C)</sub> (V)	V <sub>IL(AC)</sub> (V)	V <sub>IH(AC)</sub> (V)	V <sub>OL</sub> (V)	V <sub>OH</sub> (V)	I <sub>ol</sub> (mA)	l <sub>oh</sub>
i/O Stanuaru	Min	Max	Min	Max	Max	Min	Max	Min	I <sub>OI</sub> (IIIA)	(mA)
HSTL-18 Class I	_	V <sub>REF</sub> – 0.1	V <sub>REF</sub> + 0.1	_	V <sub>REF</sub> - 0.2	V <sub>REF</sub> + 0.2	0.4	V <sub>CCIO</sub> – 0.4	8	-8
HSTL-18 Class II	_	V <sub>REF</sub> – 0.1	V <sub>REF</sub> + 0.1	_	V <sub>REF</sub> - 0.2	V <sub>REF</sub> + 0.2	0.4	V <sub>CCIO</sub> – 0.4	16	-16
HSTL-15 Class I	_	V <sub>REF</sub> – 0.1	V <sub>REF</sub> + 0.1	_	V <sub>REF</sub> - 0.2	V <sub>REF</sub> + 0.2	0.4	V <sub>CCIO</sub> – 0.4	8	-8
HSTL-15 Class II	_	V <sub>REF</sub> – 0.1	V <sub>REF</sub> + 0.1	_	V <sub>REF</sub> - 0.2	V <sub>REF</sub> + 0.2	0.4	V <sub>CCIO</sub> – 0.4	16	-16
HSTL-12 Class I	-0.15	V <sub>REF</sub> – 0.08	V <sub>REF</sub> + 0.08	V <sub>CCIO</sub> + 0.15	V <sub>REF</sub> – 0.15	V <sub>REF</sub> + 0.15	0.25* V <sub>CCIO</sub>	0.75* V <sub>CCIO</sub>	8	-8
HSTL-12 Class II	-0.15	V <sub>REF</sub> – 0.08	V <sub>REF</sub> + 0.08	V <sub>CCIO</sub> + 0.15	V <sub>REF</sub> – 0.15	V <sub>REF</sub> + 0.15	0.25* V <sub>CCIO</sub>	0.75* V <sub>CCIO</sub>	16	-16
HSUL-12	_	V <sub>REF</sub> – 0.13	V <sub>REF</sub> + 0.13	_	V <sub>REF</sub> – 0.22	V <sub>REF</sub> + 0.22	0.1* V <sub>CCIO</sub>	0.9* V <sub>CCIO</sub>	_	

Table 20. Differential SSTL I/O Standards for Stratix V Devices

I/O Standard		V <sub>CCIO</sub> (V)			<sub>G(DC)</sub> (V)		V <sub>X(AC)</sub> (V)		V <sub>SWING(AC)</sub> (V)	
I/O Standard	Min	Тур	Max	Min	Max	Min	Тур	Max	Min	Max
SSTL-2 Class I, II	2.375	2.5	2.625	0.3	V <sub>CCIO</sub> + 0.6	V <sub>CCIO</sub> /2 – 0.2	_	V <sub>CCIO</sub> /2 + 0.2	0.62	V <sub>CCIO</sub> + 0.6
SSTL-18 Class I, II	1.71	1.8	1.89	0.25	V <sub>CCIO</sub> + 0.6	V <sub>CCIO</sub> /2 – 0.175	_	V <sub>CCIO</sub> /2 + 0.175	0.5	V <sub>CCIO</sub> + 0.6
SSTL-15 Class I, II	1.425	1.5	1.575	0.2	(1)	V <sub>CCIO</sub> /2 – 0.15	_	V <sub>CCIO</sub> /2 + 0.15	0.35	_
SSTL-135 Class I, II	1.283	1.35	1.45	0.2	(1)	V <sub>CCIO</sub> /2 – 0.15	V <sub>CCIO</sub> /2	V <sub>CCIO</sub> /2 + 0.15	2(V <sub>IH(AC)</sub> - V <sub>REF</sub> )	2(V <sub>IL(AC)</sub> - V <sub>REF</sub> )
SSTL-125 Class I, II	1.19	1.25	1.31	0.18	(1)	V <sub>CCIO</sub> /2 – 0.15	V <sub>CCIO</sub> /2	V <sub>CCIO</sub> /2 + 0.15	2(V <sub>IH(AC)</sub> - V <sub>REF</sub> )	_
SSTL-12 Class I, II	1.14	1.2	1.26	0.18	_	V <sub>REF</sub> -0.15	V <sub>CCIO</sub> /2	V <sub>REF</sub> + 0.15	-0.30	0.30

## Note to Table 20:

Table 21. Differential HSTL and HSUL I/O Standards for Stratix V Devices (Part 1 of 2)

I/O		V <sub>CCIO</sub> (V)		V <sub>DIF(</sub>	<sub>DC)</sub> (V)		V <sub>X(AC)</sub> (V)		V <sub>CM(DC)</sub> (V)			V <sub>DIF(AC)</sub> (V)	
Standard	Min	Тур	Max	Min	Max	Min	Тур	Max	Min	Тур	Max	Min	Max
HSTL-18 Class I, II	1.71	1.8	1.89	0.2	_	0.78	_	1.12	0.78	_	1.12	0.4	_
HSTL-15 Class I, II	1.425	1.5	1.575	0.2		0.68	_	0.9	0.68		0.9	0.4	_

<sup>(1)</sup> The maximum value for  $V_{SWING(DC)}$  is not defined. However, each single-ended signal needs to be within the respective single-ended limits  $(V_{IH(DC)})$  and  $V_{IL(DC)})$ .

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You typically use the interactive Excel-based Early Power Estimator before designing the FPGA to get a magnitude estimate of the device power. The Quartus II PowerPlay Power Analyzer provides better quality estimates based on the specifics of the design after you complete place-and-route. The PowerPlay Power Analyzer can apply a combination of user-entered, simulation-derived, and estimated signal activities that, when combined with detailed circuit models, yields very accurate power estimates.

For more information about power estimation tools, refer to the *PowerPlay Early Power Estimator User Guide* and the *PowerPlay Power Analysis* chapter in the *Quartus II Handbook*.

Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 2 of 7)

Symbol/	Conditions	Trai	nsceive Grade	r Speed 1	Transceiver Speed Grade 2			Trai	Unit		
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
Spread-spectrum downspread	PCle	_	0 to -0.5	_	_	0 to -0.5	_	_	0 to -0.5	_	%
On-chip termination resistors (21)	_	_	100	_	_	100	_	_	100	_	Ω
Absolute V <sub>MAX</sub> <sup>(5)</sup>	Dedicated reference clock pin	_	_	1.6	_	_	1.6	_	_	1.6	V
	RX reference clock pin	_	_	1.2	_	_	1.2	_	_	1.2	
Absolute V <sub>MIN</sub>	_	-0.4		_	-0.4	_		-0.4	_	1	V
Peak-to-peak differential input voltage	_	200	_	1600	200		1600	200	_	1600	mV
V <sub>ICM</sub> (AC coupled) <sup>(3)</sup>	Dedicated reference clock pin	1050/	1000/90	00/850 <sup>(2)</sup>	1050/	1000/90	00/850 <sup>(2)</sup>	1050/1000/900/850 (2)			mV
	RX reference clock pin	1.0/0.9/0.85 <sup>(4)</sup> 1.0/0.9/0.85 <sup>(4)</sup> 1.0/0.9/0.85 <sup>(4)</sup>				.85 <sup>(4)</sup>	V				
V <sub>ICM</sub> (DC coupled)	HCSL I/O standard for PCIe reference clock	250	_	550	250	_	550	250	_	550	mV
	100 Hz	_	_	-70	_	_	-70	_	_	-70	dBc/Hz
Transmitter	1 kHz	_	_	-90	_	_	-90	_	_	-90	dBc/Hz
REFCLK Phase Noise	10 kHz		_	-100	_	_	-100	_	_	-100	dBc/Hz
(622 MHz) <sup>(20)</sup>	100 kHz	_	_	-110	_	_	-110	_	_	-110	dBc/Hz
	≥1 MHz	_	_	-120	_	_	-120	_	_	-120	dBc/Hz
Transmitter REFCLK Phase Jitter (100 MHz) (17)	10 kHz to 1.5 MHz (PCle)	_	_	3	_	_	3	3		ps (rms)	
R <sub>REF</sub> (19)	_	_	1800 ±1%	_	_	1800 ±1%	_	_	180 0 ±1%	_	Ω
Transceiver Clock	<u> </u>			_			_			_	
fixedclk clock frequency	PCIe Receiver Detect	_	100 or 125	_	_	100 or 125	_	_	100 or 125	_	MHz

Table 26 shows the approximate maximum data rate using the 10G PCS.

Table 26. Stratix V 10G PCS Approximate Maximum Data Rate (1)

Mode <sup>(2)</sup>	Transceiver	PMA Width	64	40	40	40	32	32			
S	Speed Grade	PCS Width	64	66/67	50	40	64/66/67	32			
	1	C1, C2, C2L, I2, I2L core speed grade	14.1	14.1	10.69	14.1	13.6	13.6			
	2	C1, C2, C2L, I2, I2L core speed grade	12.5	12.5	10.69	12.5	12.5	12.5			
		C3, I3, I3L core speed grade	12.5 12.5 10.69 12.5 10.88 1								
FIFO or Register		C1, C2, C2L, I2, I2L core speed grade									
	3	C3, I3, I3L core speed grade	8.5 Gbps								
	3	C4, I4 core speed grade									
		I3YY core speed grade	10.3125 Gbps								

#### Notes to Table 26:

<sup>(1)</sup> The maximum data rate is in Gbps.

<sup>(2)</sup> The Phase Compensation FIFO can be configured in FIFO mode or register mode. In the FIFO mode, the pointers are not fixed, and the latency can vary. In the register mode the pointers are fixed for low latency.

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Table 27 shows the  $\ensuremath{V_{OD}}$  settings for the GX channel.

Table 27. Typical V $_{\text{OD}}$  Setting for GX Channel, TX Termination = 100  $\Omega$   $^{(2)}$ 

Symbol	V <sub>OD</sub> Setting	V <sub>op</sub> Value (mV)	V <sub>op</sub> Setting	V <sub>op</sub> Value (mV)
	0 (1)	0	32	640
	1 (1)	20	33	660
	2 (1)	40	34	680
	3 (1)	60	35	700
	4 (1)	80	36	720
	5 <sup>(1)</sup>	100	37	740
	6	120	38	760
	7	140	39	780
	8	160	40	800
	9	180	41	820
	10	200	42	840
	11	220	43	860
	12	240	44	880
	13	260	45	900
	14	280	46	920
<b>V</b> op differential peak to peak	15	300	47	940
typical <sup>(3)</sup>	16	320	48	960
	17	340	49	980
	18	360	50	1000
	19	380	51	1020
	20	400	52	1040
	21	420	53	1060
	22	440	54	1080
	23	460	55	1100
	24	480	56	1120
	25	500	57	1140
	26	520	58	1160
	27	540	59	1180
	28	560	60	1200
	29	580	61	1220
	30	600	62	1240
	31	620	63	1260

#### Note to Table 27:

- (1) If TX termination resistance =  $100\Omega$ , this VOD setting is illegal.
- (2) The tolerance is +/-20% for all VOD settings except for settings 2 and below.
- (3) Refer to Figure 2.

Figure 2 shows the differential transmitter output waveform.

Figure 2. Differential Transmitter Output Waveform

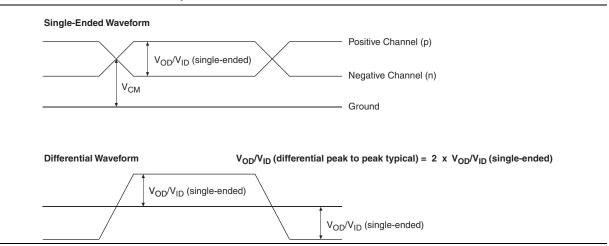


Figure 3 shows the Stratix V AC gain curves for GX channels.

Figure 3. AC Gain Curves for GX Channels (full bandwidth)



Stratix V GT devices contain both GX and GT channels. All transceiver specifications for the GX channels not listed in Table 28 are the same as those listed in Table 23.

Table 28 lists the Stratix V GT transceiver specifications.

Table 29 shows the  $\ensuremath{V_{\text{OD}}}$  settings for the GT channel.

Table 29. Typical  $\text{V}_{\text{0D}}$  Setting for GT Channel, TX Termination = 100  $\Omega$ 

Symbol	V <sub>op</sub> Setting	V <sub>op</sub> Value (mV)
	0	0
	1	200
V differential peak to peak tunical (1)	2	400
<b>V</b> <sub>OD</sub> differential peak to peak typical <sup>(1)</sup>	3	600
	4	800
	5	1000

### Note:

(1) Refer to Figure 4.

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Figure 4 shows the differential transmitter output waveform.

Figure 4. Differential Transmitter/Receiver Output/Input Waveform

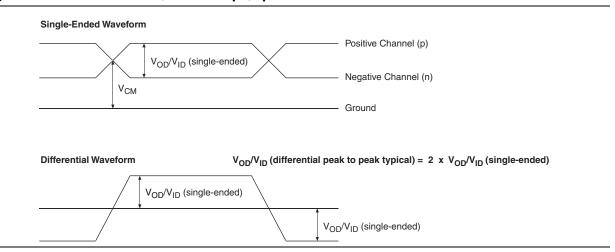


Figure 5 shows the Stratix V AC gain curves for GT channels.

Figure 5. AC Gain Curves for GT Channels

## **PLL Specifications**

Table 31 lists the Stratix V PLL specifications when operating in both the commercial junction temperature range (0° to 85°C) and the industrial junction temperature range ( $-40^{\circ}$  to  $100^{\circ}$ C).

Table 31. PLL Specifications for Stratix V Devices (Part 1 of 3)

Symbol	Parameter		Тур	Max	Unit
	Input clock frequency (C1, C2, C2L, I2, and I2L speed grades)	5	_	800 (1)	MHz
f <sub>IN</sub>	Input clock frequency (C3, I3, I3L, and I3YY speed grades)	5	_	800 (1)	MHz
	Input clock frequency (C4, I4 speed grades)	5	_	650 <sup>(1)</sup>	MHz
f <sub>INPFD</sub>	Input frequency to the PFD	5	_	325	MHz
FINPFD	Fractional Input clock frequency to the PFD	50	_	160	MHz
	PLL VCO operating range (C1, C2, C2L, I2, I2L speed grades)	600	_	1600	MHz
f <sub>vco</sub> <sup>(9)</sup>	PLL VCO operating range (C3, I3, I3L, I3YY speed grades)	600	_	1600	MHz
	PLL VCO operating range (C4, I4 speed grades)	600	_	1300	MHz
EINDUTY	Input clock or external feedback clock input duty cycle	40	_	60	%
	Output frequency for an internal global or regional clock (C1, C2, C2L, I2, I2L speed grades)	_	_	717 (2)	MHz
Гоит	Output frequency for an internal global or regional clock (C3, I3, I3L speed grades)	_	_	650 <sup>(2)</sup>	MHz
	Output frequency for an internal global or regional clock (C4, I4 speed grades)	_	_	580 <sup>(2)</sup>	MHz
	Output frequency for an external clock output (C1, C2, C2L, I2, I2L speed grades)	_	_	800 (2)	MHz
f <sub>OUT_EXT</sub>	Output frequency for an external clock output (C3, I3, I3L speed grades)	_	_	667 (2)	MHz
	Output frequency for an external clock output (C4, I4 speed grades)	_	_	553 <sup>(2)</sup>	MHz
t <sub>оитриту</sub>	Duty cycle for a dedicated external clock output (when set to <b>50%</b> )	45	50	55	%
FCOMP	External feedback clock compensation time	_	_	10	ns
DYCONFIGCLK	Dynamic Configuration Clock used for mgmt_clk and scanclk	_	_	100	MHz
Lock	Time required to lock from the end-of-device configuration or deassertion of areset	_	_	1	ms
DLOCK	Time required to lock dynamically (after switchover or reconfiguring any non-post-scale counters/delays)	_	_	1	ms
	PLL closed-loop low bandwidth		0.3		MHz
: CLBW	PLL closed-loop medium bandwidth		1.5		MHz
	PLL closed-loop high bandwidth (7)	_	4	_	MHz
PLL_PSERR	Accuracy of PLL phase shift		_	±50	ps
ARESET	Minimum pulse width on the areset signal	10	_	_	ns

Table 36. High-Speed I/O Specifications for Stratix V Devices (1), (2) (Part 2 of 4)

Combal	Conditions		C1		C2,	C2L, I	2, I2L	C3,	I3, I3I	., I3YY	C4,14			II.a.i.k
Symbol	Conditions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
Transmitter														
	SERDES factor J = 3 to 10 (9), (11), (12), (13), (14), (15), (16)	(6)	_	1600	(6)	_	1434	(6)	_	1250	(6)	_	1050	Mbps
True Differential I/O Standards	SERDES factor J ≥ 4  LVDS TX with DPA (12), (14), (15), (16)	(6)	_	1600	(6)	_	1600	(6)	_	1600	(6)		1250	Mbps
- f <sub>HSDR</sub> (data rate)	SERDES factor J = 2, uses DDR Registers	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	Mbps
	SERDES factor J = 1, uses SDR Register	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	Mbps
Emulated Differential I/O Standards with Three External Output Resistor Networks - f <sub>HSDR</sub> (data rate) (10)	SERDES factor J = 4 to 10 (17)	(6)	_	1100	(6)	_	1100	(6)	_	840	(6)		840	Mbps
t <sub>x Jitter</sub> - True Differential	Total Jitter for Data Rate 600 Mbps - 1.25 Gbps	_	_	160	_	_	160	_	_	160	_	_	160	ps
I/O Standards	Total Jitter for Data Rate < 600 Mbps	_	_	0.1	_	_	0.1	_	_	0.1	_	_	0.1	UI
t <sub>x Jitter</sub> - Emulated Differential I/O Standards	Total Jitter for Data Rate 600 Mbps - 1.25 Gbps	_	_	300	_	_	300	_	_	300	_	_	325	ps
with Three External Output Resistor Network	Total Jitter for Data Rate < 600 Mbps	_	_	0.2	_	_	0.2	_	_	0.2	_	_	0.25	UI

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Figure 7 shows the dynamic phase alignment (DPA) lock time specifications with the DPA PLL calibration option enabled.

Figure 7. DPA Lock Time Specification with DPA PLL Calibration Enabled

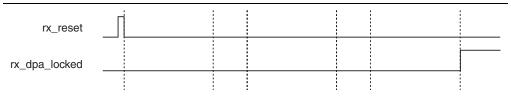


Table 37 lists the DPA lock time specifications for Stratix V devices.

Table 37. DPA Lock Time Specifications for Stratix V GX Devices Only (1), (2), (3)

Standard	Training Pattern	Number of Data Transitions in One Repetition of the Training Pattern	Number of Repetitions per 256 Data Transitions <sup>(4)</sup>	Maximum	
SPI-4	00000000001111111111	2	128	640 data transitions	
Parallel Rapid I/O	00001111	2	128	640 data transitions	
Faranei napiu 1/0	10010000	4	64	640 data transitions	
Miscellaneous	10101010	8	32	640 data transitions	
Miscellaneous	01010101	8	32	640 data transitions	

#### Notes to Table 37:

- (1) The DPA lock time is for one channel.
- (2) One data transition is defined as a 0-to-1 or 1-to-0 transition.
- (3) The DPA lock time stated in this table applies to both commercial and industrial grade.
- (4) This is the number of repetitions for the stated training pattern to achieve the 256 data transitions.

Figure 8 shows the **LVDS** soft-clock data recovery (CDR)/DPA sinusoidal jitter tolerance specification for a data rate  $\geq$  1.25 Gbps. Table 38 lists the **LVDS** soft-CDR/DPA sinusoidal jitter tolerance specification for a data rate  $\geq$  1.25 Gbps.

Figure 8. LVDS Soft-CDR/DPA Sinusoidal Jitter Tolerance Specification for a Data Rate  $\geq$  1.25 Gbps

LVDS Soft-CDR/DPA Sinusoidal Jitter Tolerance Specification

25

8.5

0.35

0.1

F1 F2

F3

F4

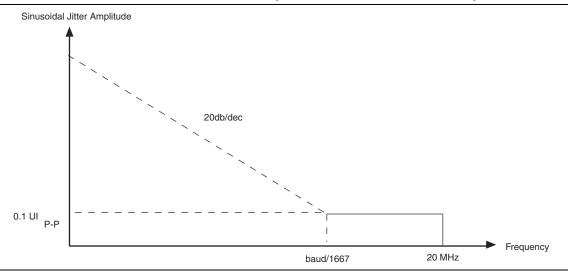
Jitter Frequency (Hz)

Table 38. LVDS Soft-CDR/DPA Sinusoidal Jitter Mask Values for a Data Rate  $\geq$  1.25 Gbps

Jitter F	requency (Hz)	Sinusoidal Jitter (UI)
F1	10,000	25.000
F2	17,565	25.000
F3	1,493,000	0.350
F4	50,000,000	0.350

Figure 9 shows the **LVDS** soft-CDR/DPA sinusoidal jitter tolerance specification for a data rate < 1.25 Gbps.

Figure 9. LVDS Soft-CDR/DPA Sinusoidal Jitter Tolerance Specification for a Data Rate < 1.25 Gbps



## DLL Range, DQS Logic Block, and Memory Output Clock Jitter Specifications

Table 39 lists the DLL range specification for Stratix V devices. The DLL is always in 8-tap mode in Stratix V devices.

Table 39. DLL Range Specifications for Stratix V Devices (1)

C1	C2, C2L, I2, I2L	C3, I3, I3L, I3YY	C4,I4	Unit
300-933	300-933	300-890	300-890	MHz

#### Note to Table 39:

(1) Stratix V devices support memory interface frequencies lower than 300 MHz, although the reference clock that feeds the DLL must be at least 300 MHz. To support interfaces below 300 MHz, multiply the reference clock feeding the DLL to ensure the frequency is within the supported range of the DLL.

Table 40 lists the DQS phase offset delay per stage for Stratix V devices.

Table 40. DQS Phase Offset Delay Per Setting for Stratix V Devices (1), (2) (Part 1 of 2)

Speed Grade	Min	Max	Unit
C1	8	14	ps
C2, C2L, I2, I2L	8	14	ps
C3,I3, I3L, I3YY	8	15	ps

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Table 40. DQS Phase Offset Delay Per Setting for Stratix V Devices (1), (2) (Part 2 of 2)

Speed Grade	Min	Max	Unit
C4,I4	8	16	ps

#### Notes to Table 40:

- (1) The typical value equals the average of the minimum and maximum values.
- (2) The delay settings are linear with a cumulative delay variation of 40 ps for all speed grades. For example, when using a -2 speed grade and applying a 10-phase offset setting to a 90° phase shift at 400 MHz, the expected average cumulative delay is [625 ps + (10 × 10 ps) ± 20 ps] = 725 ps ± 20 ps.

Table 41 lists the DQS phase shift error for Stratix V devices.

Table 41. DQS Phase Shift Error Specification for DLL-Delayed Clock (t<sub>DQS\_PSERR</sub>) for Stratix V Devices (1)

Number of DQS Delay Buffers	C1	C2, C2L, I2, I2L	C3, I3, I3L, I3YY	C4,I4	Unit
1	28	28	30	32	ps
2	56	56	60	64	ps
3	84	84	90	96	ps
4	112	112	120	128	ps

#### Notes to Table 41:

Table 42 lists the memory output clock jitter specifications for Stratix V devices.

Table 42. Memory Output Clock Jitter Specification for Stratix V Devices (1), (Part 1 of 2) (2), (3)

Clock Network	Parameter	Symbol	C1		C2, C2L, I2, I2L		C3, I3, I3L, I3YY		C4,I4		Unit
			Min	Max	Min	Max	Min	Max	Min	Max	
	Clock period jitter	t <sub>JIT(per)</sub>	-50	50	-50	50	-55	55	-55	55	ps
Regional	Cycle-to-cycle period jitter	t <sub>JIT(cc)</sub>	-100	100	-100	100	-110	110	-110	110	ps
	Duty cycle jitter	$t_{JIT(duty)}$	-50	50	-50	50	-82.5	82.5	-82.5	82.5	ps
	Clock period jitter	t <sub>JIT(per)</sub>	-75	75	<del>-</del> 75	75	-82.5	82.5	-82.5	82.5	ps
Global	Cycle-to-cycle period jitter	t <sub>JIT(cc)</sub>	-150	150	-150	150	-165	165	-165	165	ps
	Duty cycle jitter	t <sub>JIT(duty)</sub>	<del>-</del> 75	75	-75	75	-90	90	-90	90	ps

<sup>(1)</sup> This error specification is the absolute maximum and minimum error. For example, skew on three DQS delay buffers in a −2 speed grade is ±78 ps or ±39 ps.

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Table 47. Uncompressed .rbf Sizes for Stratix V Devices

Family	Device	Package	Configuration .rbf Size (bits)	IOCSR .rbf Size (bits) (4), (5)	
Stratix V E (1)	5SEE9	_	342,742,976	700,888	
Stratix V L ( )	5SEEB	_	342,742,976	700,888	

#### Notes to Table 47:

- (1) Stratix V E devices do not have PCI Express® (PCIe®) hard IP. Stratix V E devices do not support the CvP configuration scheme.
- (2) 36-transceiver devices.
- (3) 24-transceiver devices.
- (4) File size for the periphery image.
- (5) The IOCSR .rbf size is specifically for the CvP feature.

Use the data in Table 47 to estimate the file size before design compilation. Different configuration file formats, such as a hexadecimal (.hex) or tabular text file (.ttf) format, have different file sizes. For the different types of configuration file and file sizes, refer to the Quartus II software. However, for a specific version of the Quartus II software, any design targeted for the same device has the same uncompressed configuration file size. If you are using compression, the file size can vary after each compilation because the compression ratio depends on your design.

For more information about setting device configuration options, refer to *Configuration, Design Security, and Remote System Upgrades in Stratix V Devices.* For creating configuration files, refer to the *Quartus II Help*.

Table 48 lists the minimum configuration time estimates for Stratix V devices.

Table 48. Minimum Configuration Time Estimation for Stratix V Devices

Variant	Member Code	Active Serial <sup>(1)</sup>			Fast Passive Parallel (2)		
		Width	DCLK (MHz)	Min Config Time (s)	Width	DCLK (MHz)	Min Config Time (s)
	40	4	100	0.534	32	100	0.067
	A3	4	100	0.344	32	100	0.043
	A4	4	100	0.534	32	100	0.067
	A5	4	100	0.675	32	100	0.084
	A7	4	100	0.675	32	100	0.084
GX	A9	4	100	0.857	32	100	0.107
	AB	4	100	0.857	32	100	0.107
	B5	4	100	0.676	32	100	0.085
	B6	4	100	0.676	32	100	0.085
	В9	4	100	0.857	32	100	0.107
	BB	4	100	0.857	32	100	0.107
GT	C5	4	100	0.675	32	100	0.084
ui	C7	4	100	0.675	32	100	0.084

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Table 48. Minimum Configuration Time Estimation for Stratix V Devices

Variant	Member Code	Active Serial <sup>(1)</sup>			Fast Passive Parallel (2)		
		Width	DCLK (MHz)	Min Config Time (s)	Width	DCLK (MHz)	Min Config Time (s)
	D3	4	100	0.344	32	100	0.043
	D4	4	100	0.534	32	100	0.067
GS		4	100	0.344	32	100	0.043
us 	D5	4	100	0.534	32	100	0.067
	D6	4	100	0.741	32	100	0.093
	D8	4	100	0.741	32	100	0.093
E	E9	4	100	0.857	32	100	0.107
	EB	4	100	0.857	32	100	0.107

### Notes to Table 48:

## **Fast Passive Parallel Configuration Timing**

This section describes the fast passive parallel (FPP) configuration timing parameters for Stratix V devices.

## DCLK-to-DATA[] Ratio for FPP Configuration

FPP configuration requires a different DCLK-to-DATA[] ratio when you enable the design security, decompression, or both features. Table 49 lists the DCLK-to-DATA[] ratio for each combination.

Table 49. DCLK-to-DATA[] Ratio (1) (Part 1 of 2)

Configuration Scheme	Decompression	Design Security	DCLK-to-DATA[] Ratio	
	Disabled	Disabled	1	
FPP ×8	Disabled	Enabled	1	
IFF X0	Enabled	Disabled	2	
	Enabled	Enabled	2	
	Disabled	Disabled	1	
FPP ×16	Disabled	Enabled	2	
	Enabled	Disabled	4	
	Enabled	Enabled	4	

<sup>(1)</sup> DCLK frequency of 100 MHz using external CLKUSR.

<sup>(2)</sup> Max FPGA FPP bandwidth may exceed bandwidth available from some external storage or control logic.

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Table 53. AS Timing Parameters for AS  $\times$ 1 and AS  $\times$ 4 Configurations in Stratix V Devices (1), (2) (Part 2 of 2)

Symbol	Parameter	Minimum	Maximum	Units
t <sub>CD2UM</sub>	CONF_DONE high to user mode (3)	175	437	μS
t <sub>CD2CU</sub>	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	_	_
t <sub>CD2UMC</sub>	CONF_DONE high to user mode with CLKUSR option on	$t_{\text{CD2CU}}$ + (8576 $\times$ CLKUSR period)	_	_

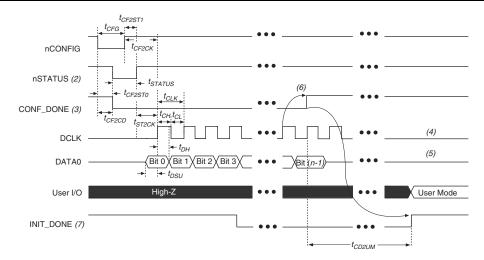
#### Notes to Table 53:

- (1) The minimum and maximum numbers apply only if you choose the internal oscillator as the clock source for initializing the device.
- $(2) \quad t_{\text{CF2CD}}, t_{\text{CF2ST0}}, t_{\text{CFG}}, t_{\text{STATUS}}, \text{ and } t_{\text{CF2ST1}} \text{ timing parameters are identical to the timing parameters for PS mode listed in Table 54 on page 63}.$
- (3) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on this pin, refer to the Initialization section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.

## **Passive Serial Configuration Timing**

Figure 15 shows the timing waveform for a passive serial (PS) configuration when using a MAX II device, MAX V device, or microprocessor as an external host.

Figure 15. PS Configuration Timing Waveform (1)



#### Notes to Figure 15:

- (1) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF\_DONE are at logic high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (2) After power-up, the Stratix V device holds nSTATUS low for the time of the POR delay.
- (3) After power-up, before and during configuration, CONF DONE is low.
- (4) Do not leave DCLK floating after configuration. You can drive it high or low, whichever is more convenient.
- (5) DATAO is available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings in the **Device and Pins Option**.
- (6) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF\_DONE is released high after the Stratix V device receives all the configuration data successfully. After CONF\_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (7) After the option bit to enable the INIT DONE pin is configured into the device, the INIT DONE goes low.

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Table 60. Glossary (Part 3 of 4)

Letter	Subject	Definitions					
	SW (sampling window)	Timing Diagram—the period of time during which the data must be valid in order to capture it correctly. The setup and hold times determine the ideal strobe position within the sampling window, as shown:  Bit Time  0.5 x TCCS RSKM Sampling Window (SW)  0.5 x TCCS					
S	Single-ended voltage referenced I/O standard	The JEDEC standard for <b>SSTL</b> and <b>HSTL</b> I/O defines both the AC and DC input signal values. The AC values indicate the voltage levels at which the receiver must meet its timing specifications. The DC values indicate the voltage levels at which the final logic state of the receiver is unambiguously defined. After the receiver input has crossed the AC value, the receiver changes to the new logic state.  The new logic state is then maintained as long as the input stays beyond the DC threshold. This approach is intended to provide predictable receiver timing in the presence of input waveform ringing:  Single-Ended Voltage Referenced I/O Standard  VIHACO  VIHACO  VILLOCO  V					
	t <sub>C</sub>	High-speed receiver and transmitter input and output clock period.					
	TCCS (channel- to-channel-skew)	The timing difference between the fastest and slowest output edges, including $t_{\text{CO}}$ variation and clock skew, across channels driven by the same PLL. The clock is included in the TCCS measurement (refer to the <i>Timing Diagram</i> figure under <b>SW</b> in this table).					
		High-speed I/O block—Duty cycle on the high-speed transmitter output clock.					
T	t <sub>DUTY</sub>	Timing Unit Interval (TUI)  The timing budget allowed for skew, propagation delays, and the data sampling window.  (TUI = $1/(\text{receiver input clock frequency multiplication factor}) = t_{\text{C}}/w$ )					
	t <sub>FALL</sub>	Signal high-to-low transition time (80-20%)  Cycle-to-cycle jitter tolerance on the PLL clock input.					
	t <sub>INCCJ</sub>						
	t <sub>OUTPJ_IO</sub>	Period jitter on the general purpose I/O driven by a PLL.					
	t <sub>OUTPJ_DC</sub>	Period jitter on the dedicated clock output driven by a PLL.					
	t <sub>RISE</sub>	Signal low-to-high transition time (20-80%)					
U	_	_					